MAX4594 SINGLE-CHANNEL 10- Ω SPST ANALOG SWITCH

SLLS639 - JANUARY 2005

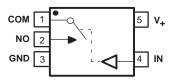
Description

The MAX4594 is a single-pole single-throw (SPST) analog switch that is designed to operate from 2 V to 5.5 V. This device can handle both digital and analog signals, and signals up to V_{+} can be transmitted in either direction.

Applications

- Sample-and-Hold Circuits
- Battery-Powered Equipment (Cellular Phones, PDAs)
- Audio and Video Signal Routing
- Communication Circuits
- PCMCIA Cards

SOT-23 OR SC-70 PACKAGE (TOP VIEW)



FUNCTION TABLE

IN	NO TO COM, COM TO NO
L	OFF
Н	ON

Features

- Low ON-State Resistance (10 Ω)
- ON-State Resistance Flatness (1.5 Ω)
- Control Inputs Are 5.5-V Tolerant
- Low Charge Injection (5 pC Max)
- 300-MHz –3-dB Bandwidth at 25°C
- Low Total Harmonic Distortion (THD) (0.05%)
- 2-V to 5.5-V Single-Supply Operation
- Specified at 5-V and 3.3-V Nodes
- -80-dB OFF Isolation at 1 MHz
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- 0.5-nA Max OFF Leakage
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)
- TTL/CMOS-Logic Compatible

Summary of Characteristics

 $V_{+} = 5 \text{ V}, T_{A} = 25^{\circ}\text{C}$

Configuration	Single Pole Single Throw (SPST)
Number of channels	1
ON-state resistance (ron)	10 Ω
ON-state resistance flatness (ron(flat))	1.5 Ω
Turn-on/turn-off time (tON/tOFF)	35 ns/40 ns
Charge injection (Q _C)	5 pC
Bandwidth (BW)	300 MHz
OFF isolation (OISO)	-80 dB at 1 MHz
Total harmonic distortion (THD)	0.05%
Leakageourrent(COM(OFF)/INO(OFF))	±0.05 nA
Power-supply current (I+)	1 μΑ
Package option	5-pin SOT-23 or SC-70

ORDERING INFORMATION

TA	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
40°C to 95°C	SOT (SOT-23) – DBV	Tape and reel	MAX4594DBVR	6SA_
-40°C to 85°C	SOT (SC-70) - DCK	Tape and reel	MAX4594DCKR	SA_

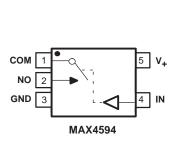
(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package. (2) DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

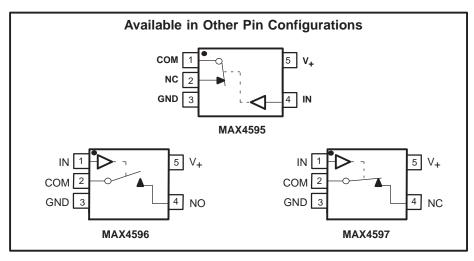


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



Pin Configurations





Absolute Minimum and Maximum Ratings(1)(2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V ₊	Supply voltage range(3)	-0.3	6	V	
V _{NO}	Analog voltage range(3)(4)		-0.3	V ₊ + 0.3	٧
ΙK	Analog port diode current	V _{NO} , V _{COM} < 0	-50		mA
I _{NO}	On-state switch current	V_{NO} , $V_{COM} = 0$ to V_{+}	-20	20	mA
I _{NO}	On-state switch current (pulsed at 1 ms, 10% duty cycle)	V_{NO} , $V_{COM} = 0$ to V_{+}	-40	40	mA
VI	Digital input voltage range(3)(4)		-0.3	6	V
lik	Digital input clamp current	V _I < 0	-50		mA
I ₊	Continuous current through V+			100	mA
IGND	Continuous current through GND		-100		mA
	Declined the small impedance (5)	DBV package		206	0000
θJΑ	Package thermal impedance(5)	DCK package		252	°C/W
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

⁽²⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

⁽³⁾ All voltages are with respect to ground, unless otherwise specified.

⁽⁴⁾ The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

⁽⁵⁾ The package thermal impedance is calculated in accordance with JESD 51-7.





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Electrical Characteristics for 5-V Supply(1) $V_+ = 4.5 \text{ V}$ to 5.5 V, $V_{IH} = 2.4 \text{ V}$, $V_{IL} = 0.8 \text{ V}$, $T_A = -40^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS			٧+	MIN	TYP	MAX	UNIT
Analog Switch						-			
Analog signal range	V _{COM} , V _{NO}					0		٧+	V
ON-state	ron	V _{NO} = 3.5 V,	Switch ON,	25°C	4.5 V		6.5	10	Ω
resistance	r _{on}	I _{COM} = 10 mA,	See Figure 13	Full	4.5 V			12	32
ON-state resistance		V _{NO} = 1.5 V, 2.5 V, 3.5 V,	Switch ON,	25°C	4.5 V		0.5	1.5	
flatness	ron(flat)	I _{COM} = 10 mA,	See Figure 13	Full	4.5 V			2	Ω
NO OFF Is also as		V _{NO} = 1 V, V _{COM} = 4.5 V,	Switch OFF,	25°C		-0.5	0.01	0.5	
OFF leakage current	INO(OFF)	or V _{NO} = 4.5 V, V _{COM} = 1 V,	See Figure 14	Full	5.5 V	-5		5	nA
COM		V _{COM} = 1 V, V _{NO} = 4.5 V,	Switch OFF,	25°C		-0.5	0.01	0.5	
OFF leakage current	ICOM(OFF)	$V_{COM} = 4.5 \text{ V}, V_{NO} = 1 \text{ V},$	See Figure 14	Full	5.5 V	-5		5	nA
NO ON leakage		V _{NO} = 1 V, V _{COM} = 1 V, or	Switch ON,	25°C	5.5.7	-1	0.01	1	^
current	INO(ON)	$V_{NO} = 4.5 \text{ V}, V_{COM} = 4.5 \text{ V},$ or $V_{NO} = 1 \text{ V}, 4.5 \text{ V}, V_{COM} = \text{Open},$	See Figure 15	Full	5.5 V	-10		10	nA
COM		$V_{COM} = 1 \text{ V}, V_{NO} = 1 \text{ V},$	Switch ON,	25°C		-1	0.01	1	
ON leakage current	ICOM(ON)	$V_{COM} = 4.5 \text{ V}, V_{NO} = 4.5 \text{ V},$ or $V_{COM} = 1 \text{ V}, 4.5 \text{ V}, V_{NO} = \text{Open},$	See Figure 15	Full	5.5 V	-10		10	nA
Digital Control In	out (IN)								
Input logic high	VIH			Full		2.4		5.5	V
Input logic low	V _{IL}			Full		0		0.8	>
Input leakage	I _{IH} , I _{IL}	$V_I = V_+ \text{ or } 0$		25°C	5 V	-1	0.03	1	μА
current	''H', 'IL	1 - 1 + 01 0		Full	J V	-1		1	μΑ

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

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Electrical Characteristics for 5-V Supply⁽¹⁾ (continued) $V_+ = 4.5 \text{ V to } 5.5 \text{ V}, T_A = -40 ^{\circ}\text{C to } 85 ^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST COND	ITIONS	T_{A}	V ₊	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time	tou	V _{NO} = 3 V,	C _L = 35 pF,	25°C	5 V		20	35	no
Turr-orr time	tON	$R_L = 300 \Omega$,	See Figure 17	Full	4.5 V to 5.5 V			45	ns
Turn-off time	tOFF	$V_{COM} = 3 V$	$C_L = 35 pF$,	25°C	5 V		25	40	ns
Turri on unio	OFF	$R_L = 300 \Omega$,	See Figure 17	Full	4.5 V to 5.5 V			50	113
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	C _L = 1 nF, See Figure 20	25°C	5 V		2	5	рС
NO OFF capacitance	C _{NO(OFF)}	V _{NO} = 0 V, f = 1 MHz,	Switch OFF, See Figure 16	25°C	5 V		8		pF
COM OFF capacitance	CCOM(OFF)	V _{COM} = 0 V, f = 1 MHz,	Switch OFF, See Figure 16	25°C	5 V		8		pF
NO ON capacitance	C _{NO(ON))}	V _{NO} = 0 V, f = 1 MHz,	Switch ON, See Figure 16	25°C	5 V		20		pF
COM ON capacitance	C _{COM(ON)}	V _{COM} = 0 V, f = 1 MHz,	Switch ON, See Figure 16	25°C	5 V		20		pF
Digital input capacitance	Cl	V _I = 0 V,	See Figure 16	25°C	5 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$, Signal = 0 dBm,	Switch ON, See Figure 18	25°C	5 V		300		MHz
OFF isolation	O _{ISO}	$R_L = 50 \Omega$, $V_{NO} = 1 V_{RMS}$, $f = 1 MHz$, $C_L = 5 pF$,	Switch OFF, See Figure 19	25°C	5 V		-80		dB
Total harmonic distortion	THD	$R_L = 600 \Omega$, $C_L = 50 pF$, $V_{SOURCE} = 5 V_{p-p}$,	f = 20 Hz to 20 kHz, See Figure 21	25°C	5 V		0.05		%
Supply	•								
Positive supply current	I ₊	$V_I = V_+$ or GND,	Switch ON or OFF	Full	5.5 V			1	μΑ

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



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Electrical Characteristics for 3-V Supply⁽¹⁾ $V_+ = 2.7 \text{ V}$ to 3.6 V, $T_A = -40 ^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST C	ONDITIONS	TA	٧+	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V _{COM} , V _{NO}					0		V ₊	V
ON-state		V _{NO} = 1.5 V,	Switch ON,	25°C	2.7 V		10	20	Ω
resistance	ron	$I_{COM} = 10 \text{ mA},$	See Figure 13	Full	2.7 V			25	22
Digital Control Inp	out (IN)								
Input logic high	VIH			Full		2		5.5	V
Input logic low	VIL			Full		0		0.8	V
Input leakage		V V == 0		25°C	0.01/	-1	0.03	1	
current	I _{IH} , I _{IL}	$V_I = V_+ \text{ or } 0$		Full	3.6 V	-1		1	μА
Dynamic									
Turn-on time		V _{NO} = 2 V,	C _L = 35 pF,	25°C	3 V		25	45	
Turn-on time	tON	$R_L = 300 \Omega$,	See Figure 17	Full	2.7 V to 3.6 V			55	ns
T off time o		V _{COM} = 2 V,	C _L = 35 pF,	25°C	3 V		30	50	
Turn-off time	tOFF	$R_L = 300 \Omega$,	See Figure 17	Full	2.7 V to 3.6 V			60	ns
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	C _L = 1 nF, See Figure 20	25°C	3 V		2	4	pC
Supply									
Positive supply current	I ₊	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	Full	3.6 V			1	μΑ

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



TYPICAL PERFORMANCE

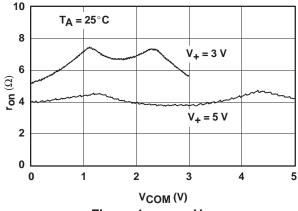


Figure 1. ron vs V_{COM}

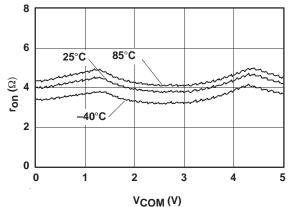


Figure 2. r_{on} vs V_{COM} ($V_{+} = 5$ V)

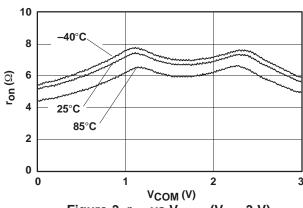
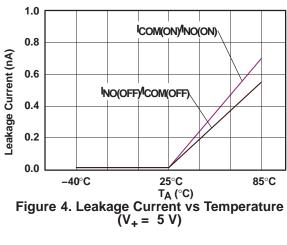


Figure 3. r_{on} vs V_{COM} ($V_{+} = 3 V$)



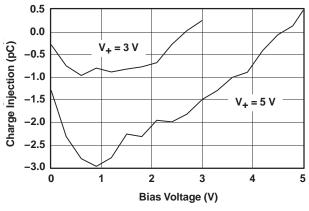


Figure 5. Charge-Injection (Q_C) vs V_{COM}

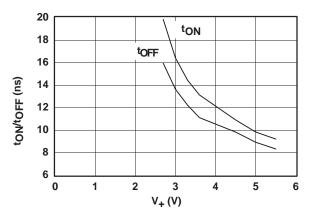


Figure 6. t_{ON} and t_{OFF} vs Supply Voltage



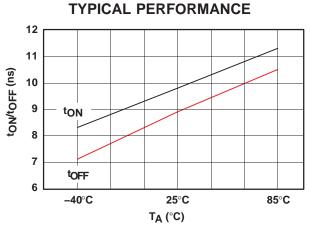


Figure 7. t_{ON} and t_{OFF} vs Temperature (V₊ = 5 V)

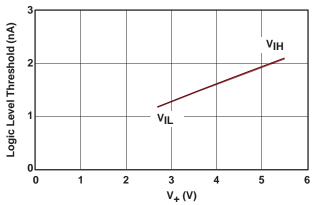


Figure 8. Logic-Level Threshold vs V₊

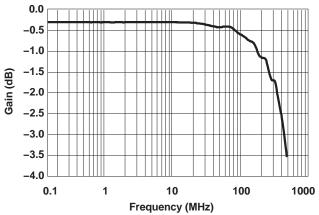


Figure 9. Bandwidth (Gain vs Frequency) $(V_+ = 5 \text{ V})$

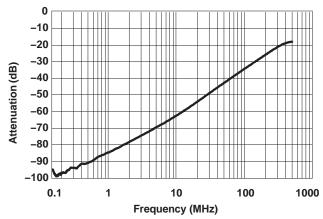


Figure 10. Off Isolation vs Frequency

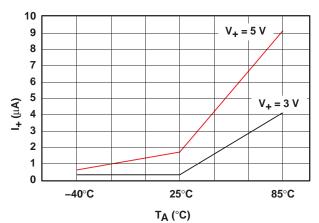


Figure 11. Power-Supply Current vs Temperature

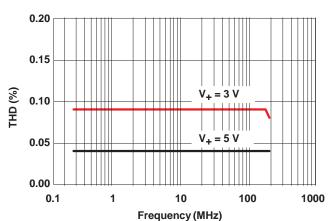


Figure 12. Total Harmonic Distortion vs Frequency



PIN DESCRIPTION

PIN NUMBER	NAME	DESCRIPTION
1	COM	Common
2	NO	Normally open
3	GND	Digital ground
4	IN	Digital control pin to connect COM to NO
5	٧+	Power supply

PARAMETER DESCRIPTION

SYMBOL	DESCRIPTION
V _C OM	Voltage at COM
V _{NO}	Voltage at NO
r _{on}	Resistance between COM and NO ports when the channel is ON
ron(flat)	Difference between the maximum and minimum value of ron in a channel over the specified range of conditions
INO(OFF)	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state
I _{NO(ON)}	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open
ICOM(OFF)	Leakage current measured at the COM port, with the corresponding channel (COM to NO) in the OFF state
ICOM(ON)	Leakage current measured at the COM port, with the corresponding channel (COM to NO) in the ON state and the output (NO) open
VIH	Minimum input voltage for logic high for the control input (IN)
V _{IL}	Maximum input voltage for logic low for the control input (IN)
VI	Voltage at the control input (IN)
I _{IH} , I _{IL}	Leakage current measured at the control input (IN)
tON	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning ON.
^t OFF	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning OFF.
QC	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NO or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$, C_L is the load capacitance, and ΔV_{COM} is the change in analog output voltage.
C _{NO(OFF)}	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
C _{NO(ON)}	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
C _{COM(OFF)}	Capacitance at the COM port when the corresponding channel (COM to NO) is OFF
C _{COM(ON)}	Capacitance at the COM port when the corresponding channel (COM to NO) is ON
Cl	Capacitance of control input (IN)
O _{ISO}	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NO to COM) in the OFF state.
BW	Bandwidth of the switch. This is the frequency in which the gain of an ON channel is -3 dB below the DC gain.
THD	Total harmonic distortion describes the signal distortion caused by the analog switch. This is defined as the ratio of root mean square (RMS) value of the second, third, and higher harmonic to the absolute magnitude of the fundamental harmonic.
l ₊	Static power-supply current with the control (IN) pin at V ₊ or GND



PARAMETER MEASUREMENT INFORMATION

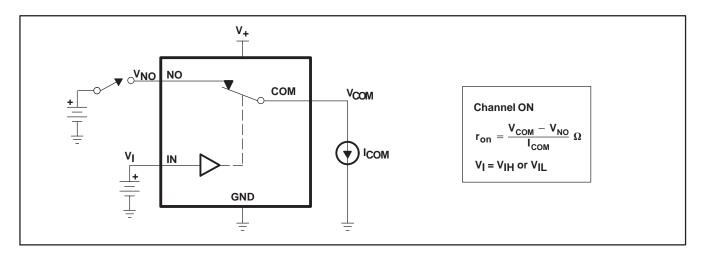


Figure 13. ON-State Resistance (ron)

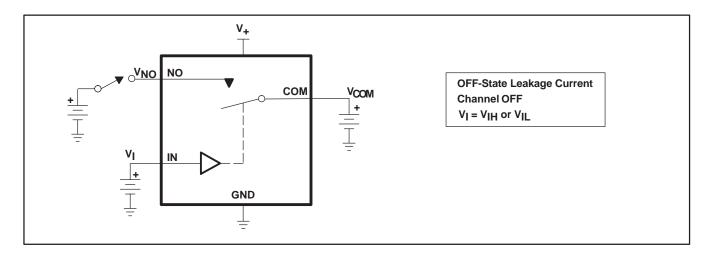


Figure 14. OFF-State Leakage Current ($I_{COM(OFF)}$, $I_{NO(OFF)}$)

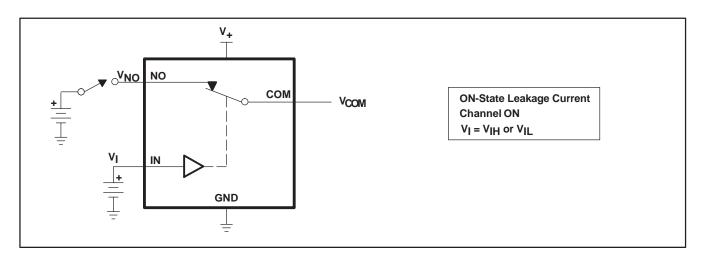


Figure 15. ON-State Leakage Current ($I_{COM(ON)}$, $I_{NO(ON)}$)



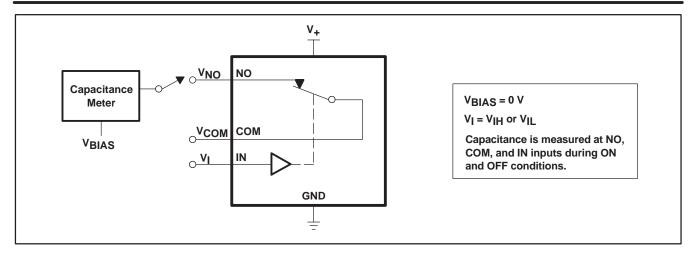
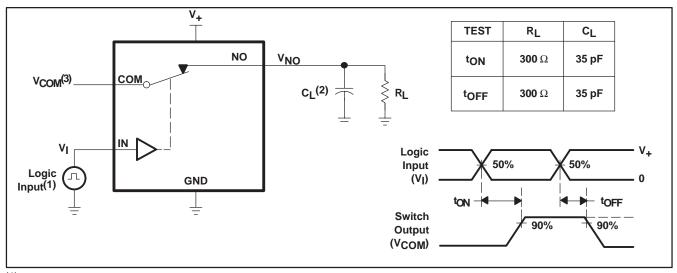


Figure 16. Capacitance (C_I, C_{COM(OFF)}, C_{COM(ON)}, C_{NO(OFF)}, C_{NO(ON)})



- (1) All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f < 5 ns. t_f < 5 ns.
- (2) C_L includes probe and jig capacitance.
- (3) See Electrical Characteristics for V_{COM}.

Figure 17. Turn-On (t_{ON}) and Turn-Off Time (t_{OFF})

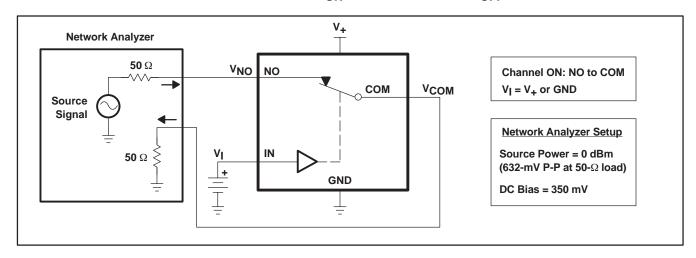


Figure 18. Bandwidth (BW)



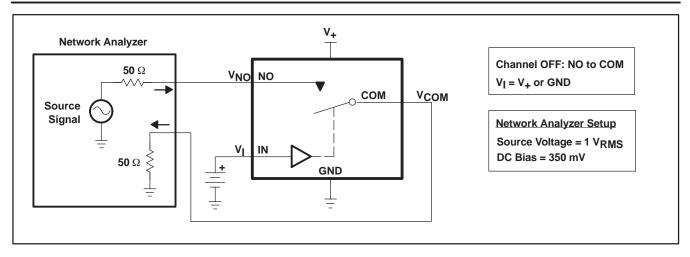
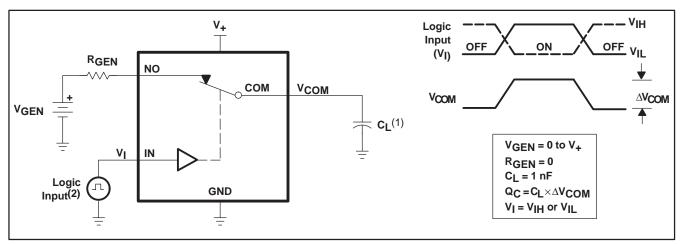
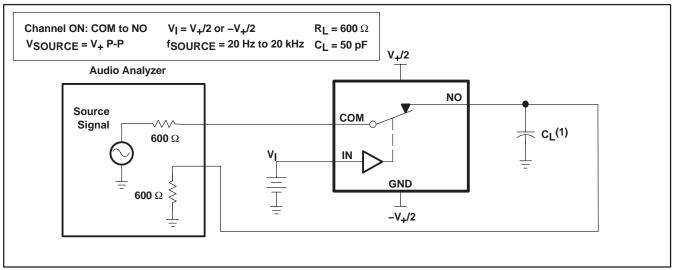


Figure 19. OFF Isolation (OISO)



- (1) C_L includes probe and jig capacitance.
- (2) All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f < 5 \text{ ns}$, $t_f < 5 \text{ ns}$.

Figure 20. Charge Injection (Q_C)



(1) C_I includes probe and jig capacitance.

Figure 21. Total Harmonic Distortion (THD)

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
MAX4594DBVR	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6SAR	Samples
MAX4594DCKR	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SAR	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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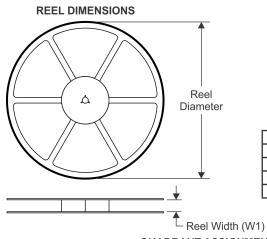
PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX4594DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
MAX4594DCKR	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3

www.ti.com 3-Aug-2017



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX4594DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
MAX4594DCKR	SC70	DCK	5	3000	202.0	201.0	28.0





NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.







NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. Reference JEDEC MO-203.

- 4. Support pin may differ or may not be present.
- 5. Lead width does not comply with JEDEC.
- 6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side





NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

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- 10. Board assembly site may have different recommendations for stencil design.



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